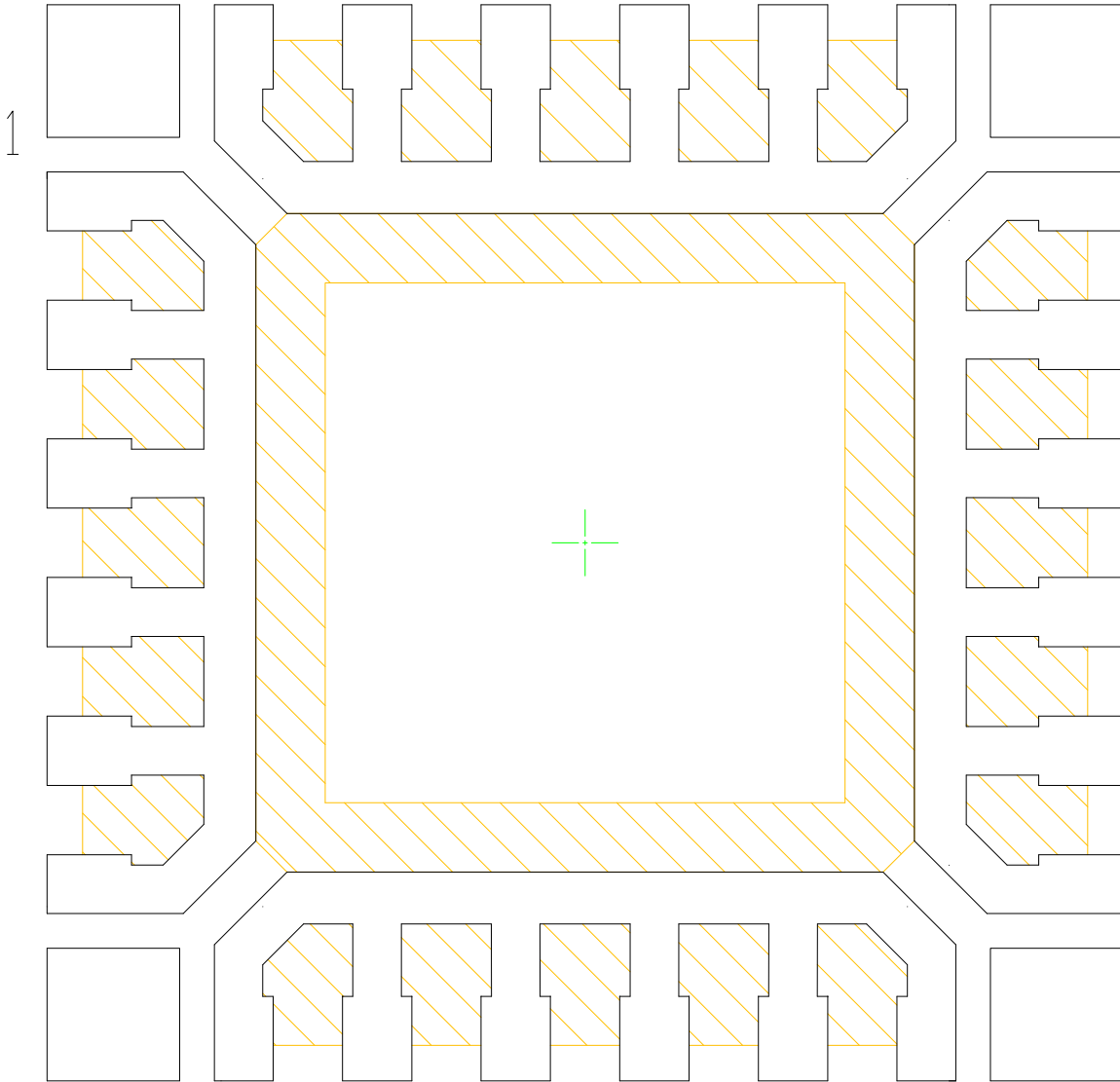



REVISIONS		
REV	DESCRIPTION	DATE
C	NEW LF PART NUMBER, INCREASE DAP AND E-PAD SIZES	08-03-17



 NiPdAu PLATING

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CUSTOMER: xxxxx	DOCUMENT #:	 www.promex-ind.com	
PROJECT NAME: xxxxx	DIE ATTACH PAD SIZE: 1.90 x 1.90 mm		
DIE SIZE, mm: xxxxx	EXPOSED PAD SIZE: 1.70 x 1.70 mm	TITLE QFN 20L 3x3 mm 0.40 PITCH BOND SHELL	
DIE THICKNESS, um: xxxxx	DAP PLATING OPTION: GROUND RING		
BOND PAD PITCH, um: xxxxx	PLATING MATERIAL: NiPdAu	LEADFRAME P/N:	REV
BOND PAD OPENING, um: xxxxx	LEADFRAME MATERIAL: C194 FH	60566	00
WIRE SIZE, um: xxxxx	LEADFRAME THICKNESS: 0.203±0.0075 mm	DO NOT SCALE	FILE NAME 20L-QFN-3X3-40P-BD.DWG SHEET 1 OF 1